













- ► Ceramic High Power
- ➤ 3838 3.55t Series
- ► Amber (600~620nm)

PRELIMINARY

N0A57S78





3838 3.55t Series



FEATURES:

- Package: Ceramic SMT Package with Glass Lens
- Forward Current: 350~500mA Forward Voltage (typ.): 2.3V

3838 3.55t Series

- Luminous Flux (typ.): 60lm@350mA
- Colour: Amber
- Dominant Wavelength: 600~620nm
- Viewing Angle: 30°
- **Materials:**
 - Resin: Glass (Water Clear)
 - L/T Finish: Ag plated
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping Parameters:**
 - Forward Voltage
 - Luminous Flux
 - **Dominant Wavelength**
- Soldering Methods: Reflow Soldering
- MSL: Level 3 according to J-STD020
- Packing: 12mm tape with max.500pcs/reel, ø180mm (7")

APPLICATIONS:

- Portable Lighting
- **Outdoor Lighting**
- **Commercial Lighting**
- **Indoor Lighting**
- **Industrial Lighting**
- Plant Grow Light



CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol Ratings		Unit
DC Forward Current	l _F	500	mA
Pulse Forward Current, D=0.01S, Duty=1/10	IPF	700	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μΑ
Junction Temperature	Tj	115	°C
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C
Soldering Temperature	T _{SOL}	260	°C
Thermal Resistance - Junction to Solder Point	R _{th}	12	°C/W

 f^* in the order of Cool White / Warm White

Electrical & Optical Characteristics (Ta=25°C)

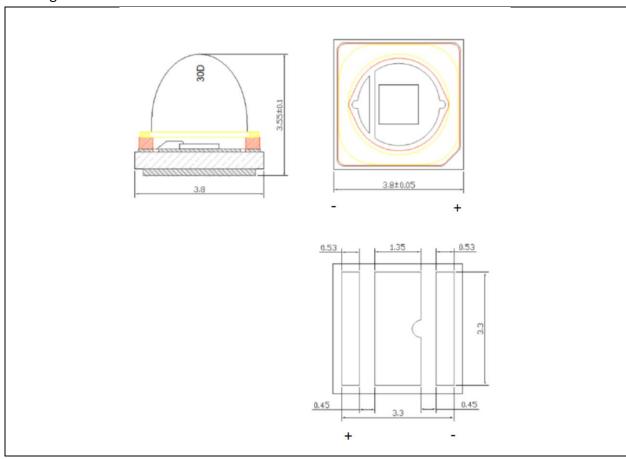
Parameter	Symbol	Values			Unit	Test
		Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	1.8		2.8	V	I _F =350mA
Luminous Flux	Ф۷	45		75	lm	I _F =350mA
Dominant Wavelength	λD	600		620	nm	I _F =350mA
Viewing Angle	2θ _{1/2}		30		deg	I _F =350mA

^{1.} Radiant Flux (Φ_V) ±5%, Forward Voltage (V_F) ±0.06V, Viewing angle($2\theta_{1/2}$) ±10°



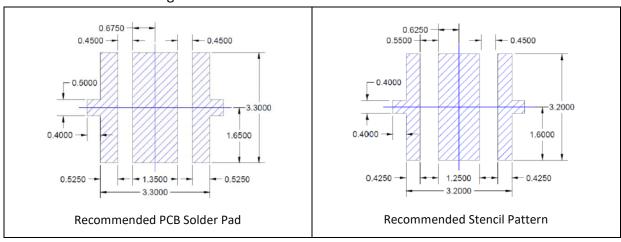
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

Recommended Soldering Pad Dimension:

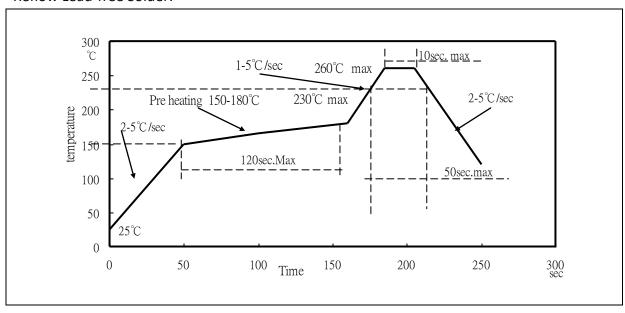


- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.12mm with angle tolerance ±0.5°.



RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



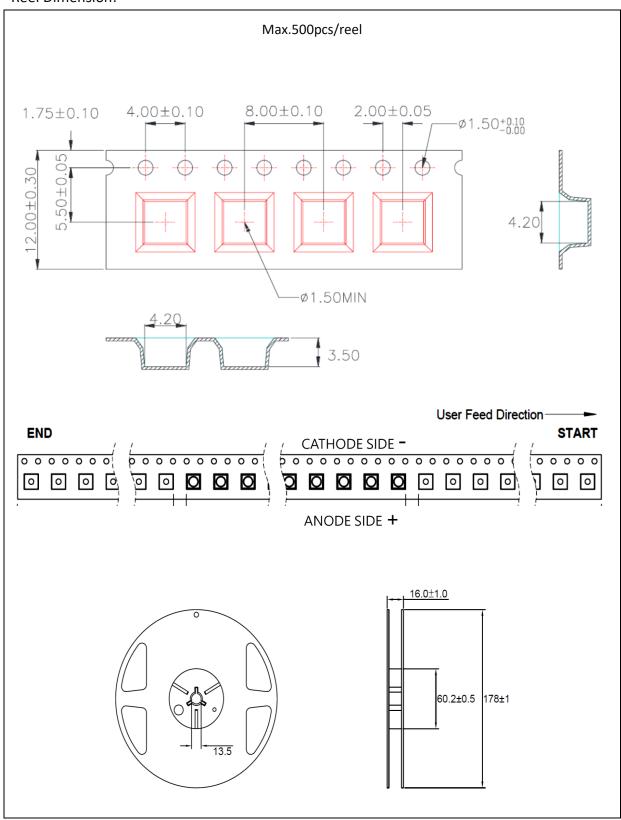
Note:

- 1. Maxima reflow soldering: 2 times.
- 2. The recommend reflow temperature is 240°C. The maxima soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

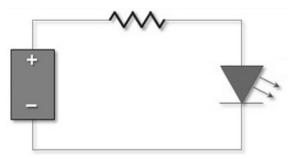
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	20/05/2022	Datasheet set-up.
A1.1	01/02/2025	New datasheet format.